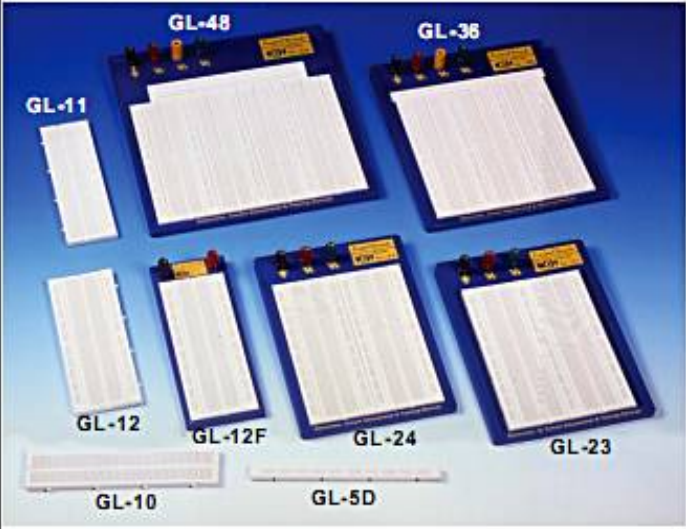


GL-12 Breadboard

Universal 840 Tie-Point Solderless PCB Breadboard Project Board

GL SERIES



GL-11	740	Tie points
GL-48	3260	Tie points
GL-36	2420	Tie points
GL-12	840	Tie points
GL-12F	840	Tie points
GL-24	1680	Tie points
GL-23	1580	Tie points
GL-10	640	Tie points
GL-5D	100	Tie points

N:NICKEL PLATED S:SILVER PLATED

Materials: Insulator: thermoplastic.

Specifications:

- model: GL-12
- dimension (l-w-h) in mm : 172-65-10
- tie points : 840
- 5 interconnect clip : 128
- 25 interconnect clip : 8
- IC capacity 14 pin : 9
- weight : 130 grams
- Temperature range: -20 ~ +80°C.
- Contact resistance: 100 mΩ max.
- Insulation resistance: 1000MΩ min.
- Dielectric withstanding voltage: 500V AC per 1 minute.
- Group of 5 connected terminals
- Bus of 25 connected terminals